
Towards the resilient factory

Insights from semiconductor production for "Industrie 4.0"

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Fraunhofer IISB

Industry 4.0 and Cyber Physical Systems (CPS)

Semiconductor Manufacturing

Standards

Advanced Process Control (APC)

From APC-enabled equipment to CPS

Summary and Outlook

Materials



Technologies &

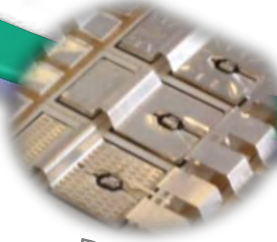
Electronic Systems

From Materials to Power Electronic Applications –
Everything from One Source

Manufacturing



Devices &



Reliability



Automotive Electronics



Energy Electronics

Semiconductors • Power Electronics

Fraunhofer Institute for Integrated Systems and Device Technology (IISB) and Chair of Electron Devices (LEB)



LEB:

- 700 m² office and lab area
- 1000 m² cleanroom (ISO Cl 3/4)
- Staff: approx. 50

Fraunhofer IISB:

- 8390 m² office and lab area
- 525 m² cleanroom (ISO Cl 3)
- Staff: approx. 290
- Subsidiaries:



*Center for Automotive
Power Electronics and
Mechatronics
ZKLM, Nuremberg*



*Technology Center
for Semiconductor
Materials THM,
Freiberg (Saxony)*

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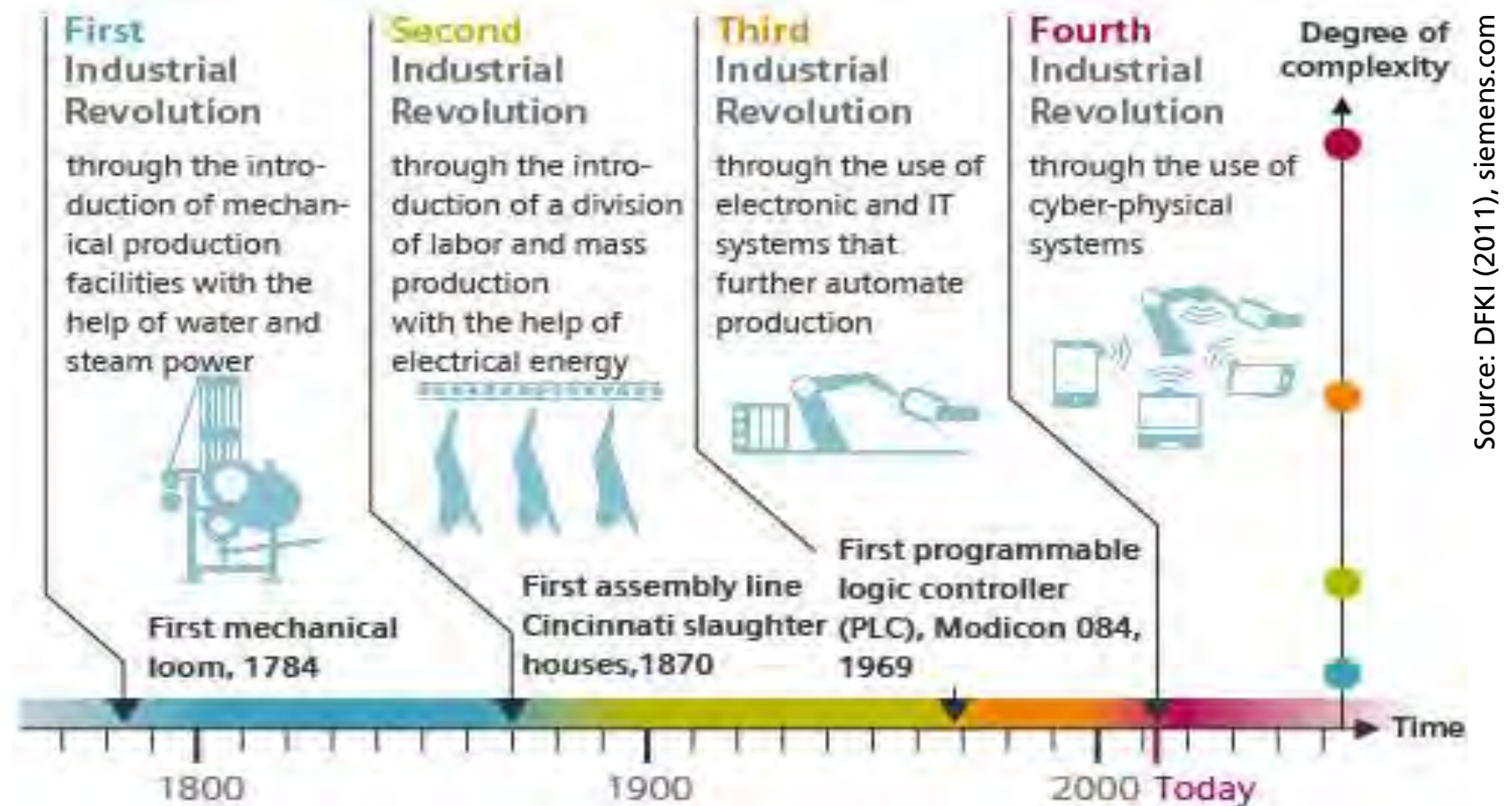
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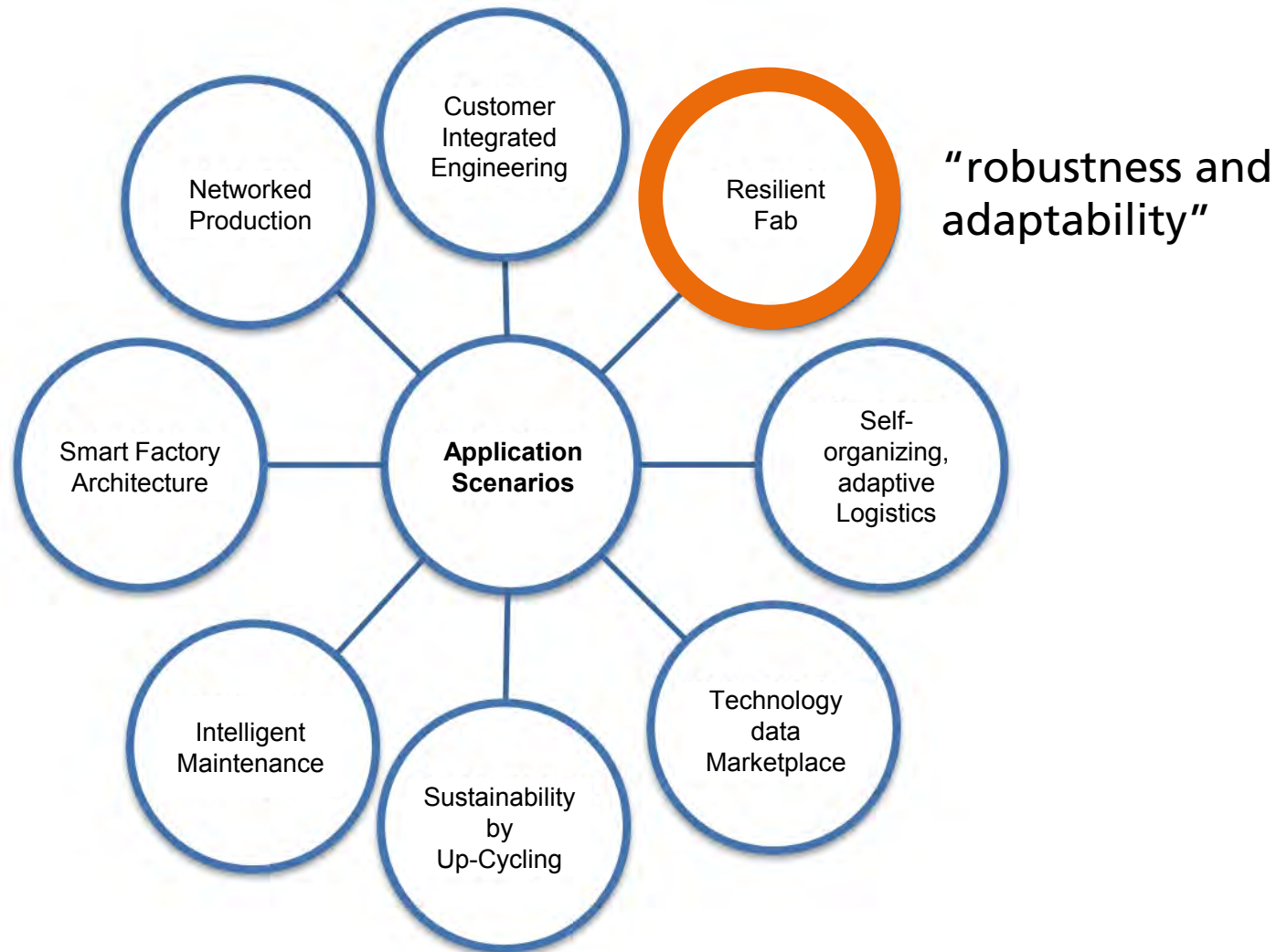
Industry 4.0

History



Industry 4.0

Application Scenarios



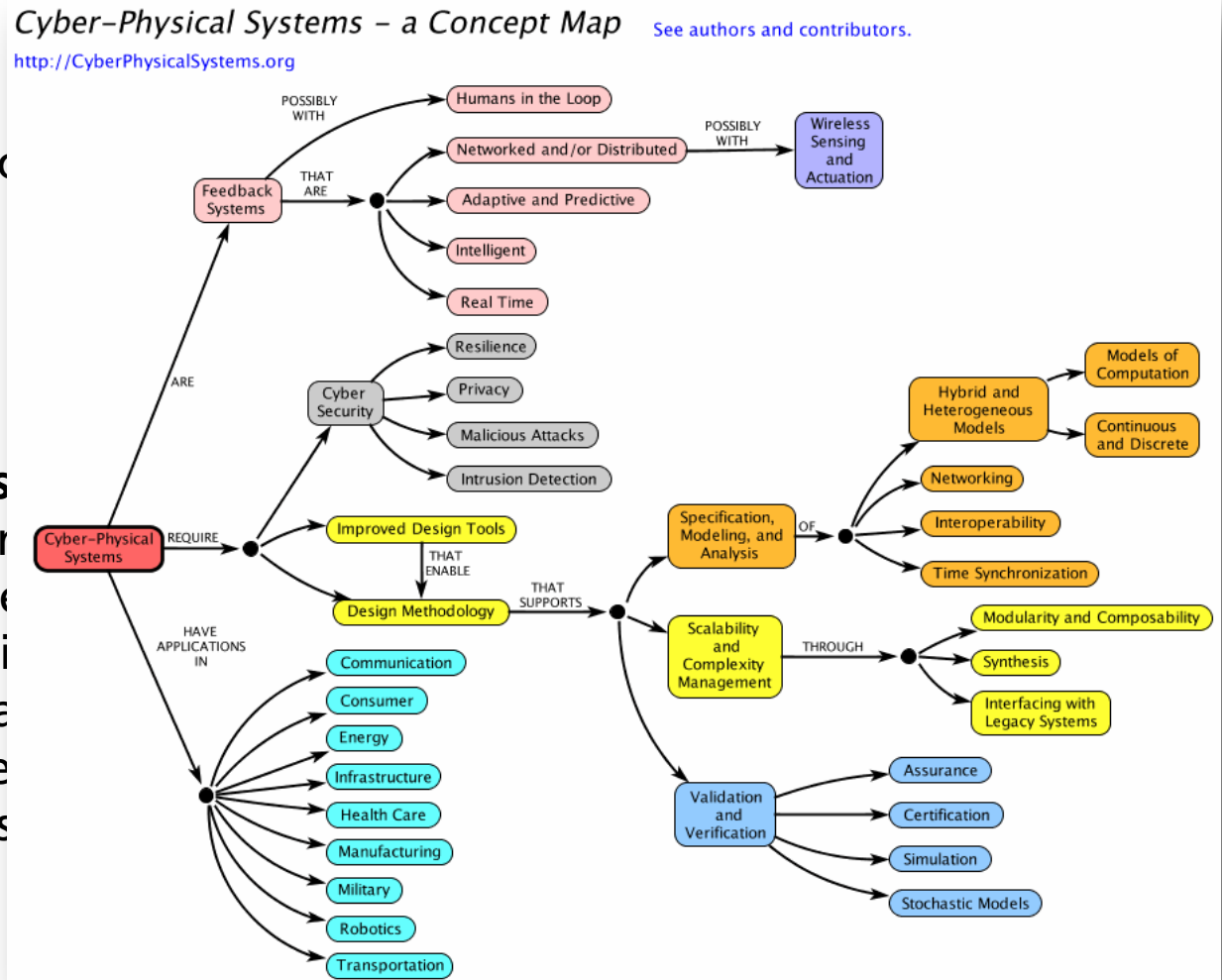
Industry 4.0

Cyber Physical Systems

Apparently: CPS is a for
... what is a CPS?

Wikipedia:

A cyber-physical system (CPS) is a system of interacting elements controlling physical processes. The elements of a cyber-physical system are cyber elements (e.g., computers, communication networks, control systems) and physical elements (e.g., sensors, actuators, mechanical systems, electrical systems, chemical systems, automotive, chemical manufacturing, transportation, appliances). This general concept is embedded systems elements, and less physical elements.



Industry 4.0

Many Open Questions

“... 85% of the experts are convinced that most German companies have no clear understanding of Industry 4.0”



Pressemeldungen | 06.08.2014

eco: Wirtschaft ohne Orientierung bei Industrie 4.0

Dr. Bettina Horster: „Viele Unternehmen sind mit Industrie 4.0 schlichtweg überfordert“

Der Umgang der deutschen Wirtschaft mit Industrie 4.0 ist weitgehend durch Orientierungslosigkeit und Überforderung geprägt. Dies ist die Kernaussage einer aktuellen Expertenumfrage von eco – Verband der deutschen Internetwirtschaft e. V. 85 Prozent der von eco befragten Fachleute sind der festen Überzeugung, dass die meisten Unternehmen in Deutschland keine klare Vorstellung davon haben, was Industrie 4.0 eigentlich ist und wie sie aussehen wird. 94 Prozent der Experten halten die deutsche Wirtschaft durch die für Industrie 4.0 erforderliche Zusammenschaltung von Hardware, Software und Telekommunikation für schlichtweg überfordert.

Industry 4.0

Many Open Questions

“32% of the managers claim that they have not yet heard or read about Industry 4.0”

07.04.2015

Jedem dritten Produktionsbetrieb ist Industrie 4.0 kein Begriff

- Umfrage unter Führungskräften in den industriellen Kernbranchen
- Aussteller zeigen die vernetzte Produktion in der „Bitkom Innovation Area Industrie 4.0“ auf der Hannover Messe
- 45 Vorträge und 10 Podiumsdiskussionen beim „Forum Industrie 4.0“

Berlin, 7. April 2015 - Industrie 4.0 ist in Medien, Politik und Wirtschaft hochaktuell und auf der diesjährigen Hannover Messe das bestimmende Thema. Dennoch ist der Begriff in deutschen Fertigungsunternehmen noch nicht hinlänglich bekannt. Das zeigt eine Umfrage im Auftrag des Digitalverbands Bitkom. Demnach sagen die Führungskräfte von gut jedem dritten Unternehmen (32 Prozent) aus der Automobilbranche, dem Maschinenbau, der chemischen Industrie sowie der Elektroindustrie, dass sie bislang noch nichts über Industrie 4.0 gehört oder gelesen haben. Befragt wurden je Branche 100 Unternehmen mit mindestens 100 Mitarbeitern. „Angesichts der hohen Bedeutung von Industrie 4.0 macht dieses Ergebnis nachdenklich“, sagt Winfried Holz, Mitglied des Bitkom-Präsidiums. „Die Zukunft der einzelnen Branchen und des Wirtschaftsstandorts Deutschland hängt entscheidend davon ab, wie zügig und gut es gelingt, die klassische Produktion zu digitalisieren und neue Geschäftsmodelle zu entwickeln. Wer sich jetzt nicht mit dem Thema auseinandersetzt, könnte den Anschluss verpassen.“

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Semiconductor Manufacturing

... what comes to mind



Sources: tinfacts.ie, computer-oiger.de, xbtllabs.com, de.wikipedia.org, dailytech.com

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Semiconductor Manufacturing

A semiconductor view on "Industry 4.0"

In Semiconductor FrontEnd factories elements of a „Smart Factory“ are already realized.



Dr. T. Kaufmann,
Infineon

11th
Innovationsforum
for automation,
2014, Dresden



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Standards

Some history

Most famous standard: „SECS/GEM“

- 1978: Hewlett-Packard proposed that standards be established for communications among semiconductor manufacturing equipment.
- 1980/1982: SEMI published the SECS-1/SECS-II standards
- 1992: GEM standard published
- Continued: HSMS, GEM300, EDA/Interface A, ...



„Semiconductor Equipment and Materials International“

- Founded in 1970
- Tradeshows (SEMICON), conferences, networking
- **Industry standards** (> 800 standards and safety guidelines)
- USA - Japan - Europa - Taiwan - Korea - China
- www.semi.org

GEM

- Defines equipment behavior

SECS II

- Data items, messages

SECS 1

- Electrics/mechanics, transactions

Overview of 300 mm SEMI Standards

Carriers:
E1.9 (Cassette)
E23 (Cassette Transfer Parallel I/O)
E47.1 (FOUP)
E103 (SWIT) → withdrawn
E119 (FOBIT)
M31 (FOSB)

Frames (BEOL):
G74 (Tape Frame)
G87 (Plastic Tape Frame)
G77 (Wafer Frame Cassette)
G82 (Load Port for Frame Cassettes)

Interfaces:
Equipment – Facilities:
E97 Facility Package Integration, Monitoring & Control
F107 Process Equipment Adapter Plates
Human:
E95 Human Interface for Semiconductor Manufacturing Equipment

E110 (Operator Interface)

E22.1 (Cluster-Tool End Effector)

E21.1 (Cluster-Tool Module Interface)

Wafers:
M1, M57, M62

E144 (RF Air Interface)

E57 (Kinematic Coupling)

E62 (FIMS)

E15.1 (Load Port)
S28 (Safety of Robots & Load Ports)

E84 (Carrier Hand off Parallel I/O)

E101 (EFEM)

E64 (Card Docking Interface)

E83 (PGV Docking Flange)

E70 (Tool Accommodation Process)
E72 (Equipment Footprint, Height, Weight)
E76 (Process Equipment Points of Connection to Facility Services)

Equipment-/ Process-specific standards:
E117 (Reticle Load Port)
E152 (EUV Pod)

Integrated Metrology (IM):
E127 (integrated measurement module communication)
E141 (Ellipsometer equipment)

Automated Material Handling System (AMHS):
E82 (Interbay/ Intrabay AMHS SEM (IBSEM))
E88 (Stocker SEM)
E153 AMHS SEM Specification

E85 (Stocker Interface)

E63 (BOLTS-M) and/ or
E92 (BOLTS-Light) or
E131 (IMM)

E25 (Cluster-Tool Access) and/ or
E26.1 (Cluster-Tool Footprint)

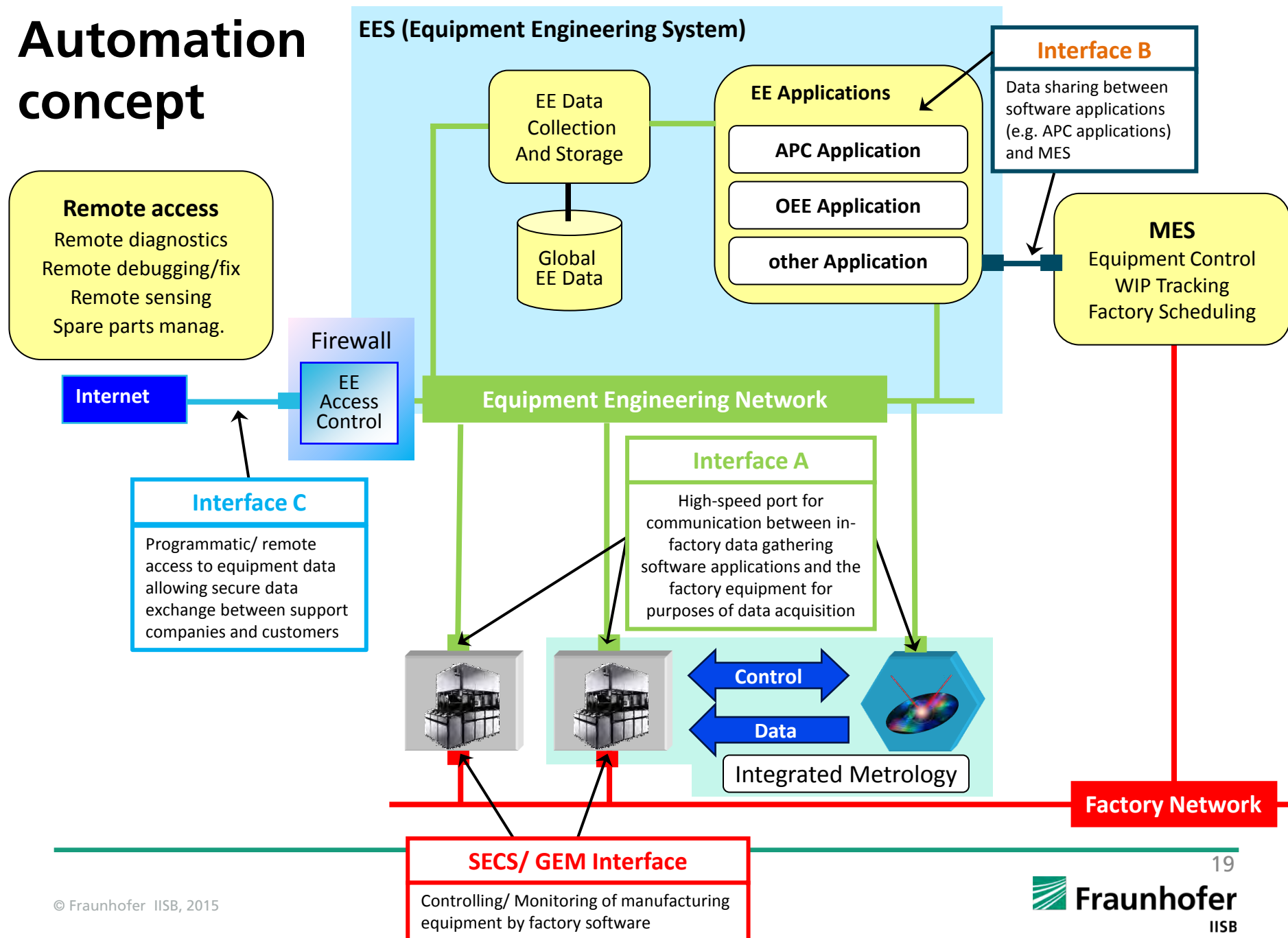
FOUP Loader

EFEM

Handling

Process module

Automation concept



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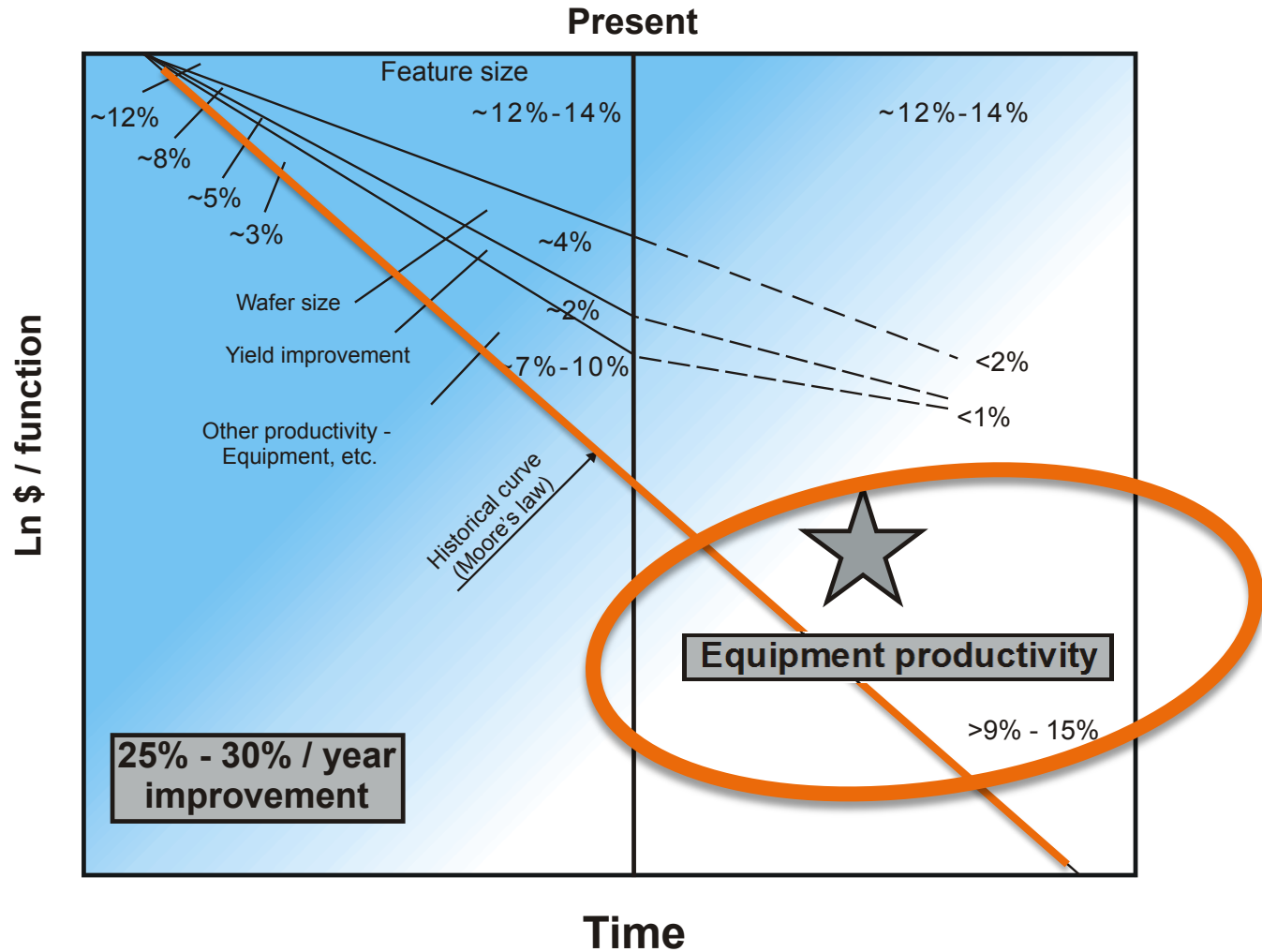
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Summary and Outlook

APC in semiconductor manufacturing

The productivity gap

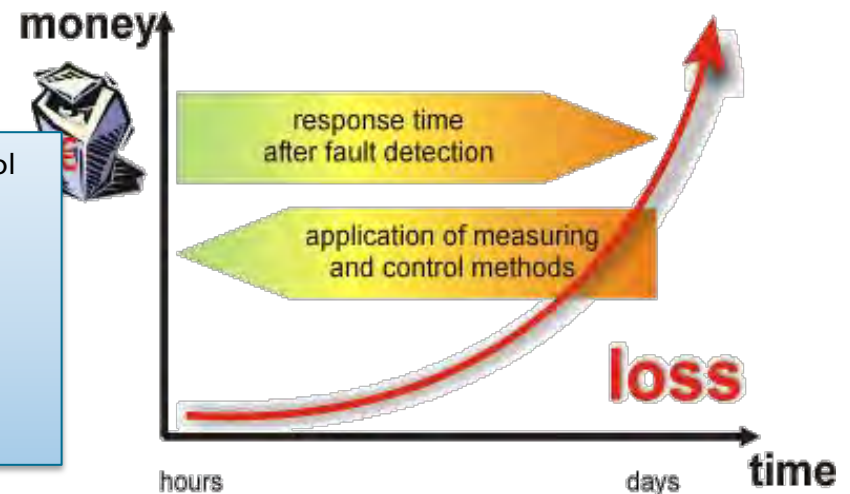


APC in semiconductor manufacturing

„Big data“ and Advanced Process Control

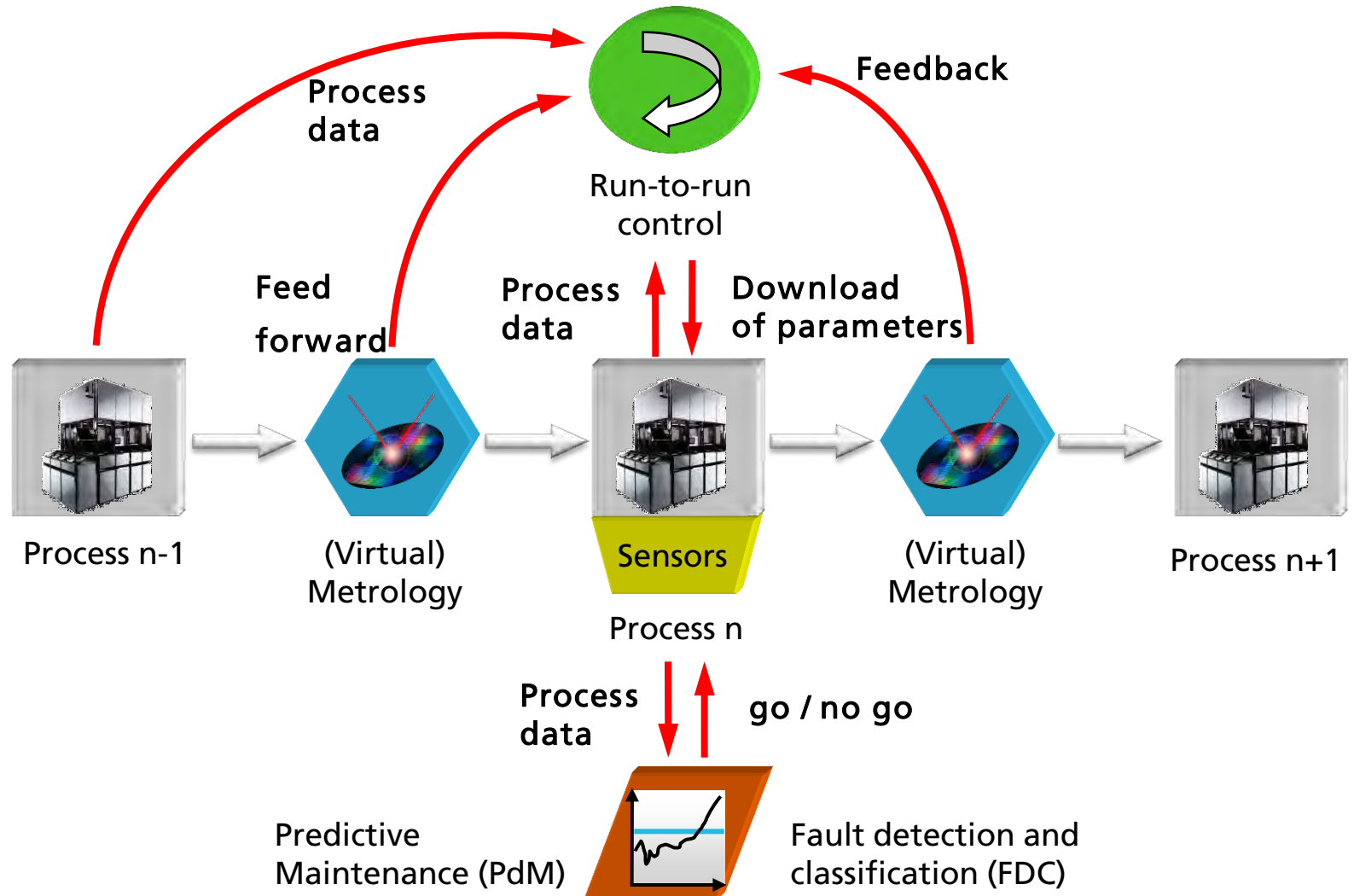
- Objective: Ensure high productivity and product quality
- Fundamental goals of APC (“Advanced Process Control”)
 - to apply measures for process control close to the process
 - to automate control actions
- Typical APC methods (SEMI E133):
 - SPC, FDC, FP, RtR, VM, PdM
- Basis for APC:
 - Metrology data
 - Data from equipment & processes
 - Logistics data

Statistical Process Control
Fault Detection and Classification
Fault Prediction
Run-to-Run Control
Virtual Metrology
Predictive Maintenance



APC in semiconductor manufacturing

Interaction of APC elements

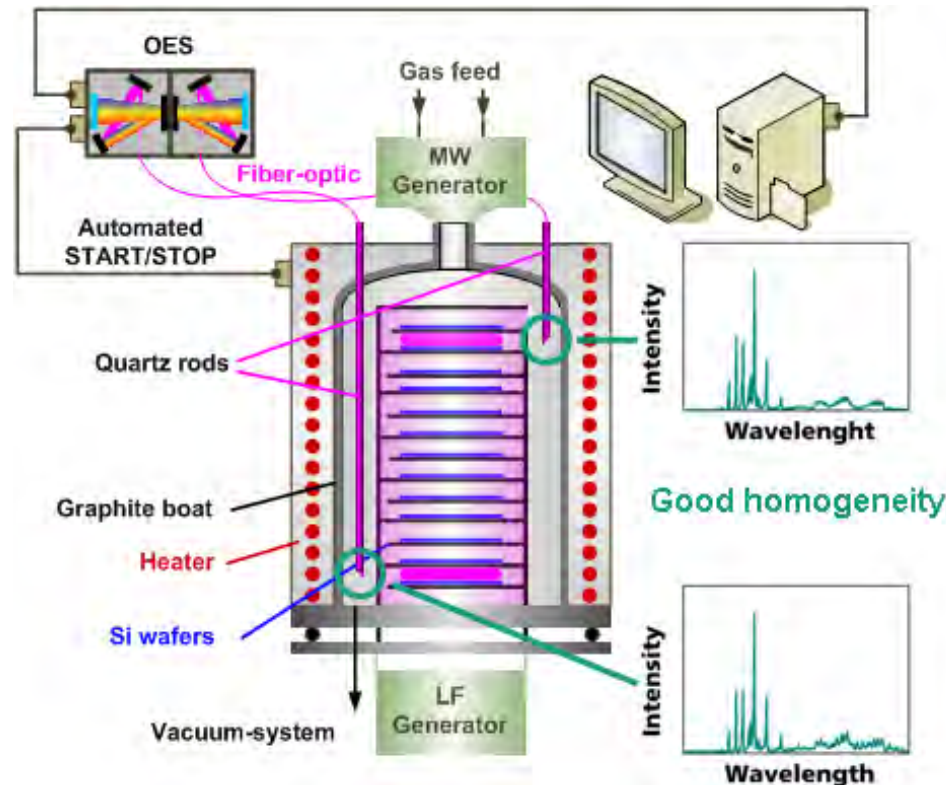


APC in semiconductor manufacturing

Examples for productivity enhancement by APC

Real-time control of plasma processes by integrated OES

Higher productivity at equipment level

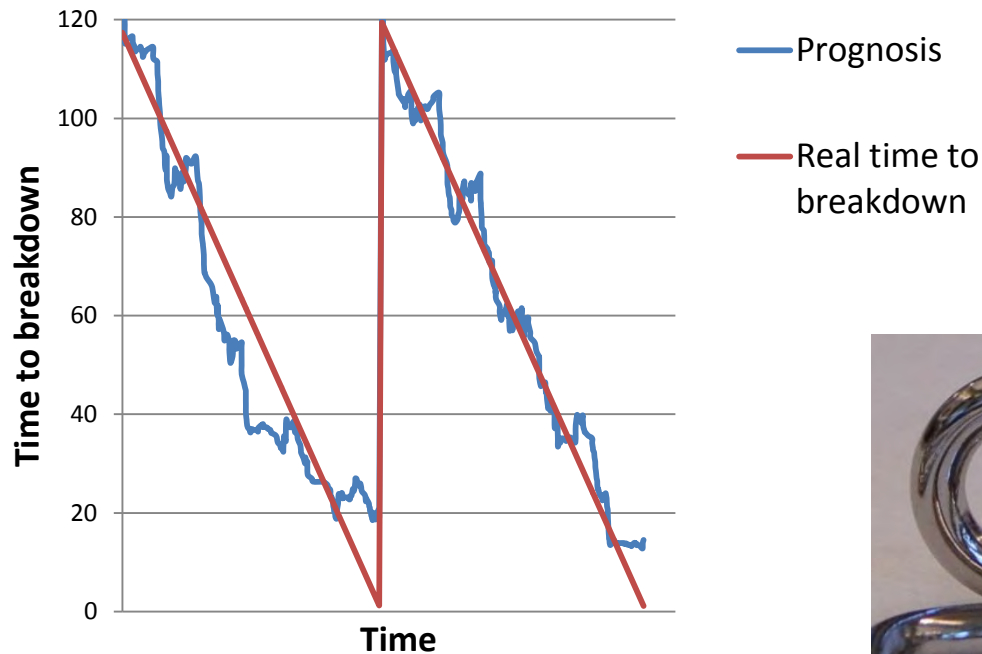


APC in semiconductor manufacturing

Examples for productivity enhancement by APC

Prediction of maintenance events by PdM

Optimized tool operation and maintenance planning

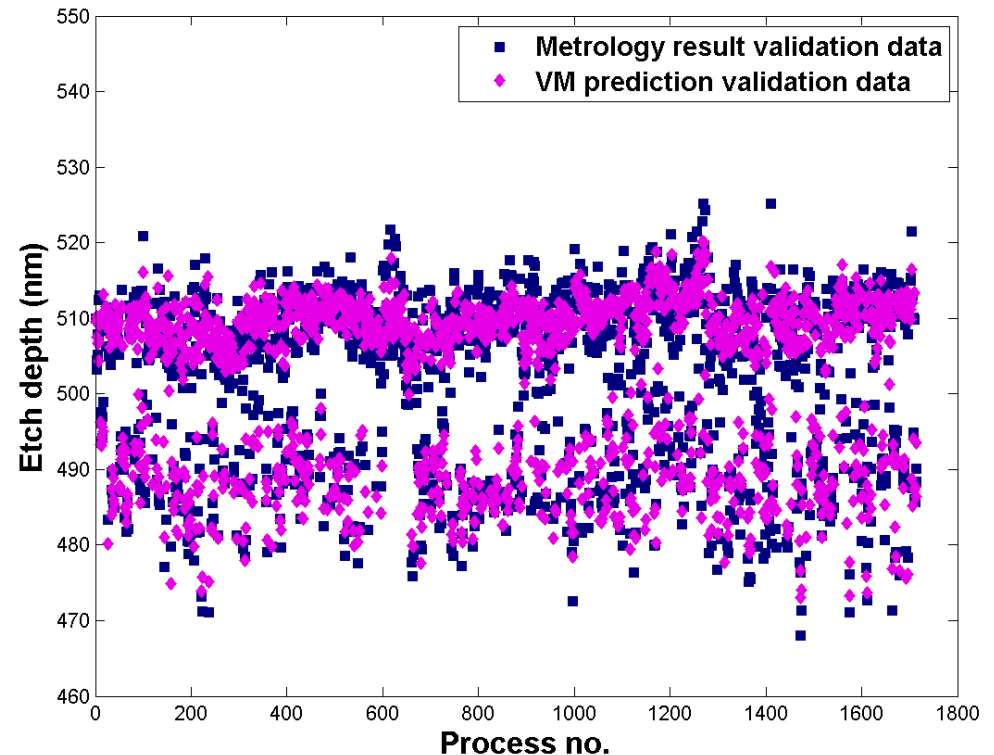
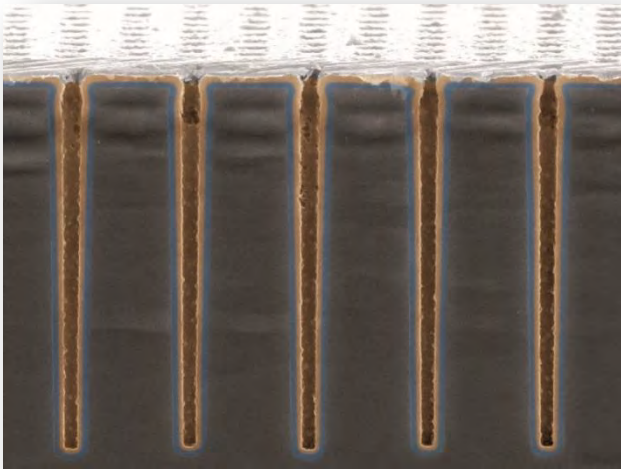


APC in semiconductor manufacturing

Examples for productivity enhancement by APC

Prediction of quality parameters by virtual metrology

Tight process control by “measuring” every wafer



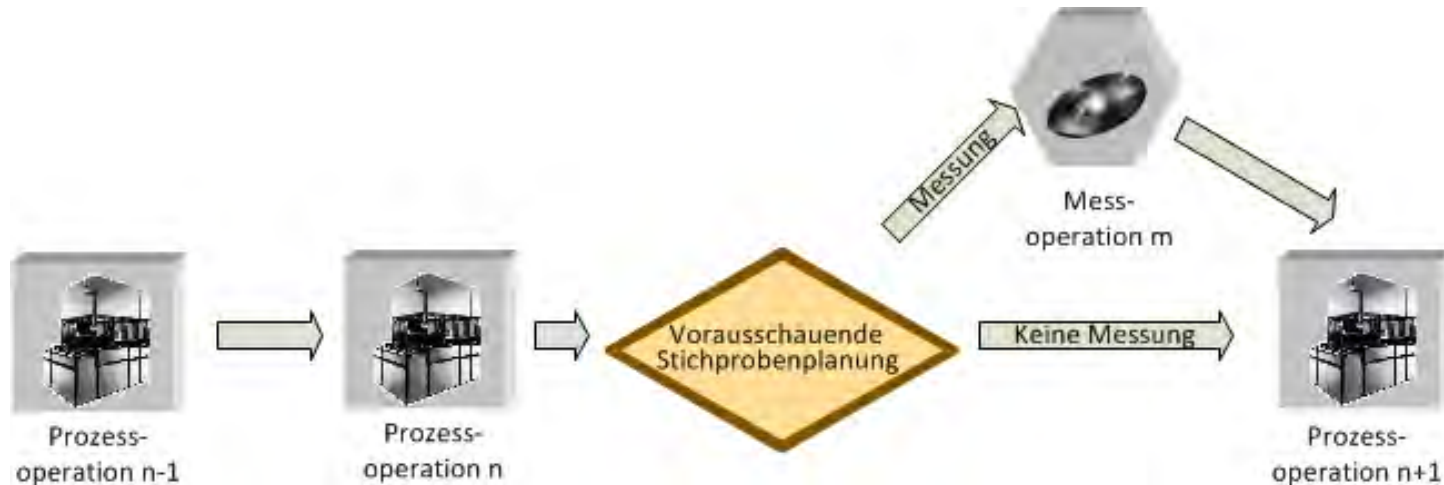
Prediction of etch depth by VM -
predicted data vs. metrology results

APC in semiconductor manufacturing

Examples for productivity enhancement by APC

Flexible sampling and predictive scheduling with $W@R^*$ indicator

Best quality control with minimized number of measurements

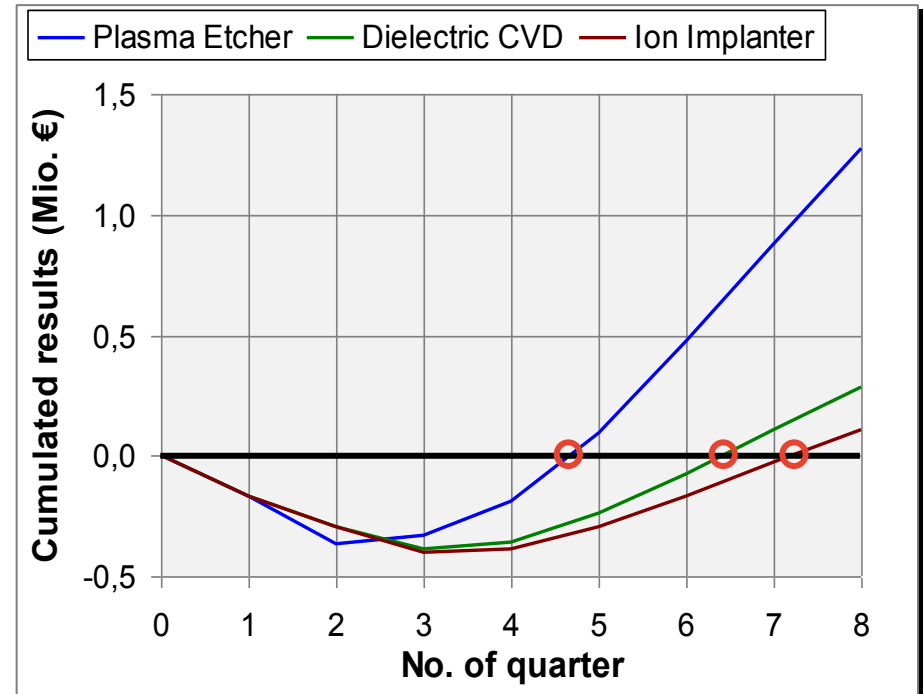


* Wafers at risk = amount of uncontrolled wafers

APC in semiconductor manufacturing

Estimation of benefits – RoI

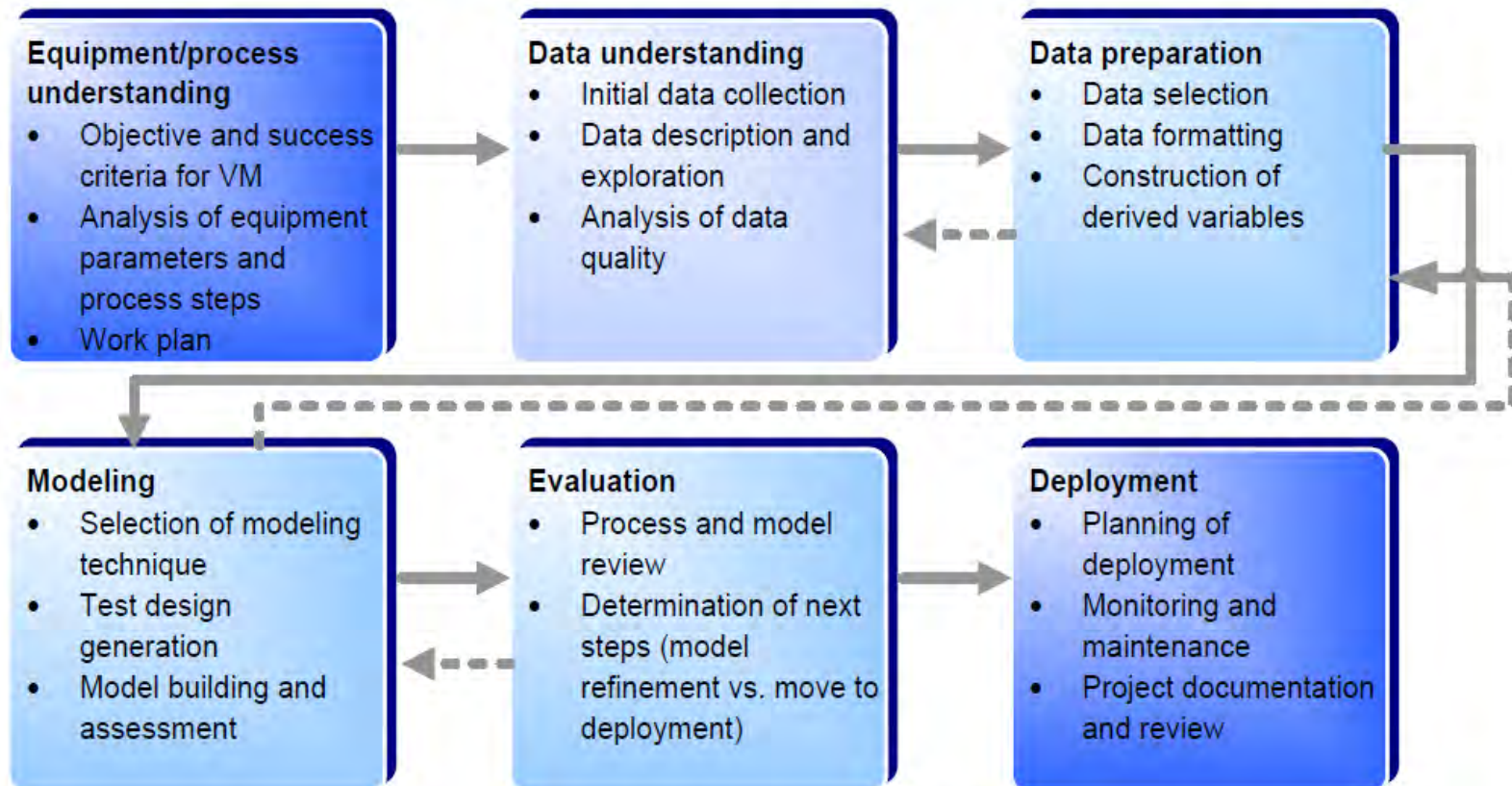
- Investment assessment for APC in semiconductor manufacturing
- Identification of economic effects from APC – possible savings and cost
- Development of models to calculate economical figures of merit, e.g., RoI, payback period
- FMEA to identify and quantify new risks from the introduction of APC



APC in semiconductor manufacturing

Structured approach for development and deployment

Phases in VM/PdM development as adapted from the Cross-Industry Standard Process for Data-Mining (CRISP-DM)



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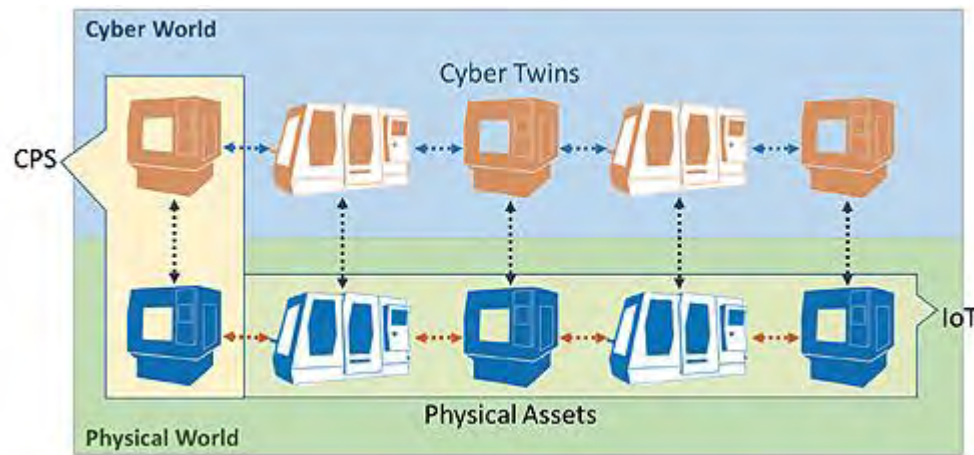
Summary and Outlook

From APC-enabled equipment to CPS

Cyber Physical Systems – basis for the resilient fab

Properties of a Cyber Physical System

- CPS are based on connectivity (IoT)
- CPS run complex analytics
- CPS extract knowledge from raw data



A cyber-physical system is characterized by a physical asset, such as a machine, and its digital twin; basically a software model that mimics the behavior of the physical asset. In contrast, the IoT in common parlance is generally limited to the physical assets, not their digital models.

http://www.designworldonline.com/big-future-for-cyber-physical-manufacturing-systems/#_

From APC-enabled equipment to CPS

Cyber Physical Systems – basis for the resilient fab

**Data collection from various sources
(internal, external)**

„Self“-Perception

**Control of
physical assets**

INTERNAL

Communication

EXTERNAL

**Perception of
environment**

**According action/
re-action**



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Summary and Outlook

Summary & Outlook

The chance of working together

„Industry 4.0“

- Mostly linear production processes
- Combine physical objects with “intelligence” → “cyber-physical systems”

Custom Tailored Production

Resilient Fab

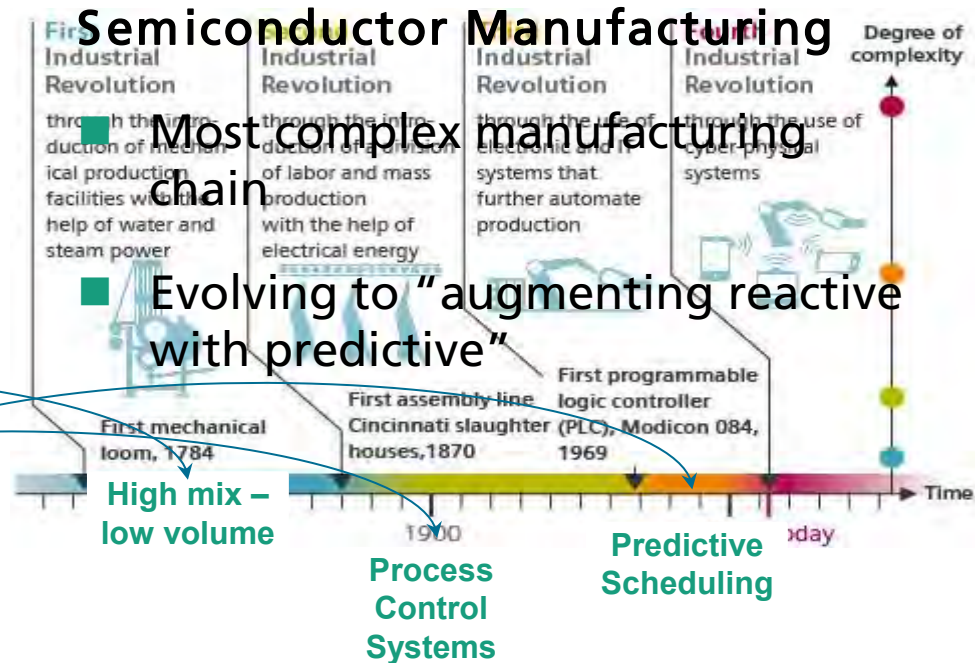
Self-organizing, adaptive Logistics

Smart Factory Architecture

Intelligent Maintenance

Smart Fab

Predictive Maintenance

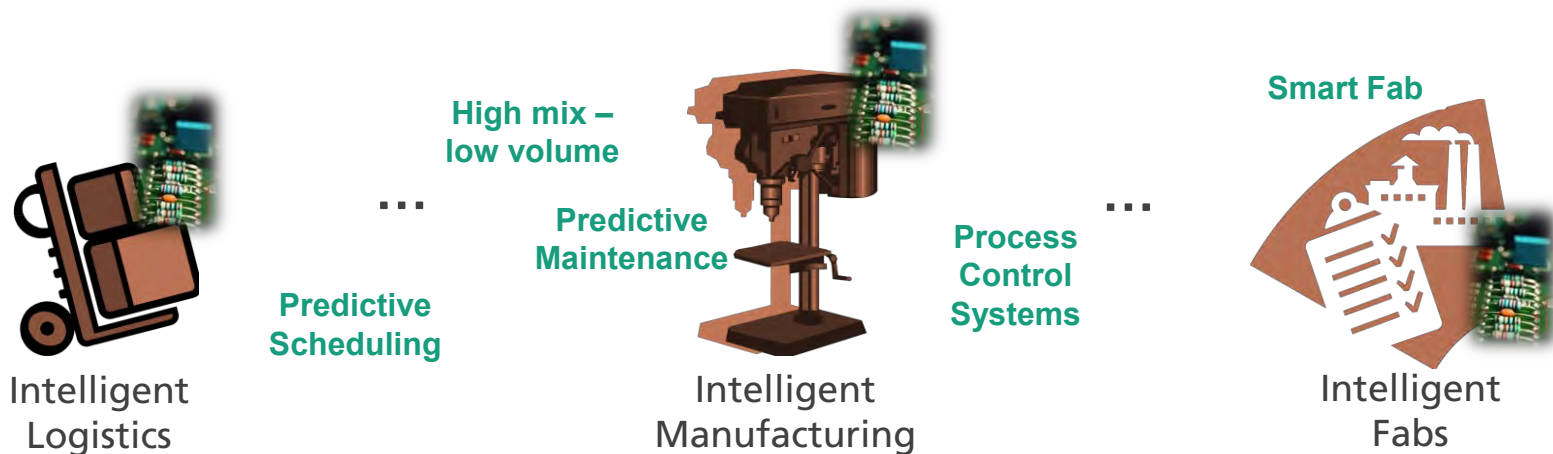


Summary & Outlook

The chance of working together

Mission of Fraunhofer IISB

- Merge “Industry 4.0” trend with “augmenting reactive with predictive” trend
- From “APC-enhanced equipment” to “cyber-physical systems”



Summary & Outlook

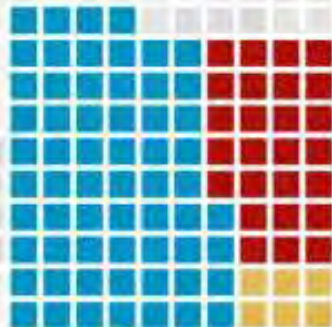
The chance of working together

ALLEINGÄNGE

Die Unternehmen packen die Digitalisierung meist auf eigene Faust an, anstatt zu kooperieren.

Kooperieren Sie mit Forschungseinrichtungen oder Thinktanks?

N=94



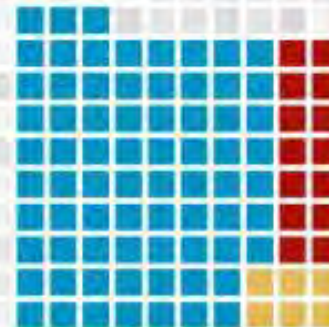
28 %
ja

6 %
nein, aber
geplant

66 %
nein und
nicht geplant

Kooperieren Sie mit Start-ups?

N=93



15 %
ja

6 %
nein, aber
geplant

78 %
nein und
nicht geplant

QUELLE: ACCENTURE

Summary & Outlook

The chance of working together

Lessons learned from APC in semiconductor manufacturing

1. Collaborate (competitors, universities, ...)
2. Know your process
3. Make use of standards
4. Good to have data from >1 year of production
5. Take care of data quality
6. Combine knowledge of data experts and process experts
7. Go for low-hanging fruits ...
8. ... but avoid "island-solutions"
9. Collaborate



Summary & Outlook

The chance of working together

Achievements in semiconductor manufacturing

- Standards and automation concepts evolved over more than 35 years
- Proven as basis for improving productivity

Potential for other industries

- “Hold on to what is good” – knowledge and definitions
- Well experienced R&D and suppliers available

The chance of working together

- From APC-enhanced equipment to cyber-physical systems
- Semiconductor manufacturing: strategic partnerships with other industries, spearheading with products and “manufacturing science”

Acknowledgment

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- the European ENIAC project IMPROVE,
- the EU projects SEA-NET and SEAL.

Thanks

for your attention!

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